COM'L: -7/10/12/15/20, Q-12/15/20 IND: -12/14/18/24

MACH210A-7/10/12 MACH210-12/15/20 MACH210AQ-12/15/20

Lattice Semiconductor

High-Density EE CMOS Programmable Logic

DISTINCTIVE CHARACTERISTICS

- 44 Pins
- 64 Macrocells
- 7.5 ns tpp Commercial 12 ns tpD Industrial
- 133 MHz fcnt
- 38 Inputs; 210A Inputs have built-in pull-up resistors
- Peripheral Component Interconnect (PCI) compliant
- 32 Outputs
- 64 Flip-flops; 2 clock choices
- 4 "PAL22V16" blocks with buried macrocells
- Pin-compatible with MACH110, MACH111, MACH211, and MACH215

GENERAL DESCRIPTION

The MACH210 is a member of the high-performance EE CMOS MACH 2 device family. This device has approximately six times the logic macrocell capability of the popular PAL22V10 without loss of speed.

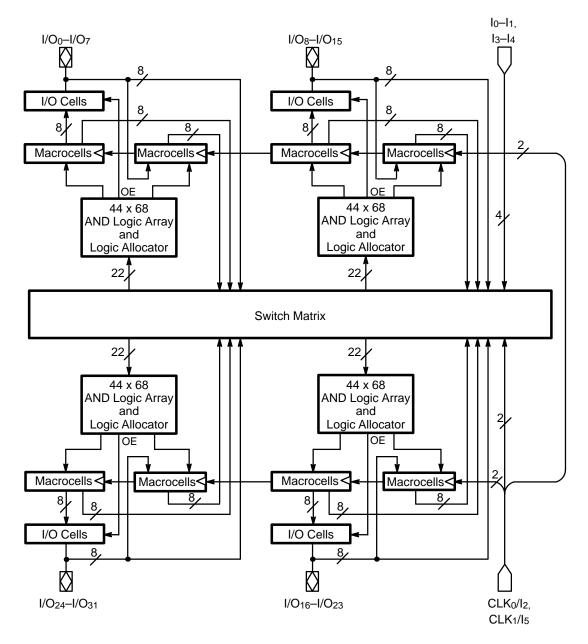
The MACH210 consists of four PAL blocks interconnected by a programmable switch matrix. The four PAL blocks are essentially "PAL22V16" structures complete with product-term arrays and programmable macrocells, including additional buried macrocells. The switch matrix connects the PAL blocks to each other and to all input pins, providing a high degree of connectivity between the fully-connected PAL blocks. This allows designs to be placed and routed efficiently.

The MACH210 has two kinds of macrocell: output and buried. The MACH210 output macrocell provides registered, latched, or combinatorial outputs with programmable polarity. If a registered configuration is chosen, the register can be configured as D-type or T-type to help reduce the number of product terms. The register type decision can be made by the designer or by the software. All output macrocells can be connected to an I/O cell. If a buried macrocell is desired, the internal feedback path from the macrocell can be used, which frees up the I/O pin for use as an input.

The MACH210 has dedicated buried macrocells which, in addition to the capabilities of the output macrocell, also provide input registers or latches for use in synchronizing signals and reducing setup time requirements.

> Publication# 14128 Rev I Amendment /0 Issue Date: May 1995

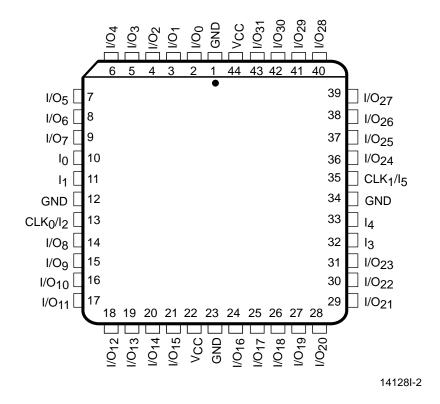
BLOCK DIAGRAM



14128I-1

CONNECTION DIAGRAM Top View

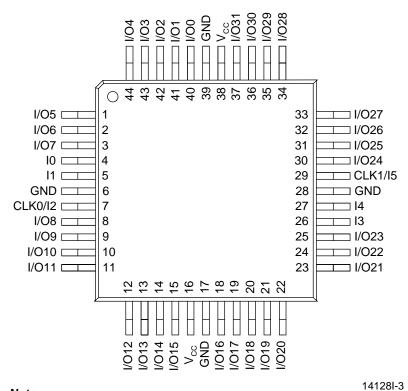
PLCC



Note: Pin-compatible with MACH110, MACH111, MACH211, and MACH215.

CONNECTION DIAGRAM Top View

TQFP



Note: Pin-compatible with MACH111 and MACH211.

PIN DESIGNATIONS

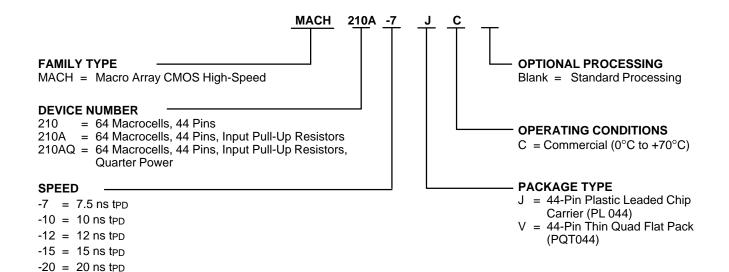
CLK/I = Clock or Input

GND = Ground I = Input

I/O = Input/Output Vcc = Supply Voltage

ORDERING INFORMATION Commercial Products

Programmable logic products for commercial applications are available with several ordering options. The order number (Valid Combination) is formed by a combination of:



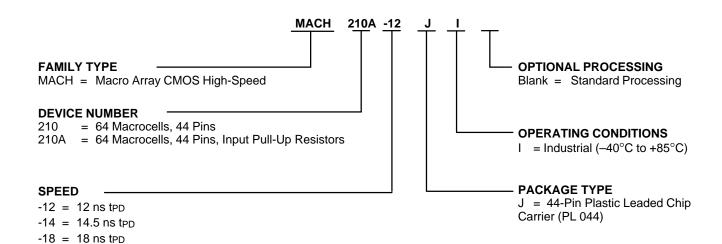
Valid Combinations				
MACH210A-7	2			
MACH210A-10	JC, VC			
MACH210A-12				
MACH210-12				
MACH210-15				
MACH210-20	JC			
MACH210AQ-12	30			
MACH210AQ-15				
MACH210AQ-20				

Valid Combinations

The Valid Combinations table lists configurations planned to be supported in volume for this device. Consult your local sales office to confirm availability of specific valid combinations or to check on newly released combinations.

ORDERING INFORMATION Industrial Products

Programmable logic products for industrial applications are available with several ordering options. The order number (Valid Combination) is formed by a combination of:



Valid Combinations		
MACH210A-12		
MACH210A-14		
MACH210-14	JI	
MACH210-18		
MACH210-24		

 $-24 = 24 \text{ ns t}_{PD}$

Valid Combinations

The Valid Combinations table lists configurations planned to be supported in volume for this device. Consult your local sales office to confirm availability of specific valid combinations or to check on newly released combinations.

FUNCTIONAL DESCRIPTION

The MACH210 consists of four PAL blocks connected by a switch matrix. There are 32 I/O pins and 4 dedicated input pins feeding the switch matrix. These signals are distributed to the four PAL blocks for efficient design implementation. There are two clock pins that can also be used as dedicated inputs.

The MACH210A inputs and I/O pins have built-in pull-up resistors. While it is always a good design practice to tie unused pins high, the 210A pull-up resistors provide design security and stability in the event that unused pins are left disconnected.

The PAL Blocks

Each PAL block in the MACH210 (Figure 1) contains a 64-product-term logic array, a logic allocator, 8 output macrocells, 8 buried macrocells, and 8 I/O cells. The switch matrix feeds each PAL block with 22 inputs. This makes the PAL block look effectively like an independent "PAL22V16" with 8 buried macrocells.

In addition to the logic product terms, two output enable product terms, an asynchronous reset product term, and an asynchronous preset product term are provided. One of the two output enable product terms can be chosen within each I/O cell in the PAL block. All flip-flops within the PAL block are initialized together.

The Switch Matrix

The MACH210 switch matrix is fed by the inputs and feedback signals from the PAL blocks. Each PAL block provides 16 internal feedback signals and 8 I/O feedback signals. The switch matrix distributes these signals back to the PAL blocks in an efficient manner that also provides for high performance. The design software automatically configures the switch matrix when fitting a design into the device.

The Product-term Array

The MACH210 product-term array consists of 64 product terms for logic use, and 4 special-purpose product terms. Two of the special-purpose product terms provide programmable output enable; one provides asynchronous reset, and one provides asynchronous preset.

The Logic Allocator

The logic allocator in the MACH210 takes the 64 logic product terms and allocates them to the 16 macrocells as needed. Each macrocell can be driven by up to 16 product terms. The design software automatically configures the logic allocator when fitting the design into the device.

Table 1 illustrates which product term clusters are available to each macrocell within a PAL block. Refer to Figure 1 for cluster and macrocell numbers.

Table 1. Logic Allocation

Mad	rocell	Available
Output	Buried	Clusters
M ₀	M ₁	C ₀ , C ₁ , C ₂ C ₀ , C ₁ , C ₂ , C ₃
M ₂	Мз	C ₁ , C ₂ , C ₃ , C ₄ C ₂ , C ₃ , C ₄ , C ₅
M4	M ₅	C ₃ , C ₄ , C ₅ , C ₆ C ₄ , C ₅ , C ₆ , C ₇
M ₆	M ₇	C ₅ , C ₆ , C ₇ , C ₈ C ₆ , C ₇ , C ₈ , C ₉
M ₈	M ₉	C ₇ , C ₈ , C ₉ , C ₁₀ C ₈ , C ₉ , C ₁₀ , C ₁₁
M 10	M ₁₁	C ₉ , C ₁₀ , C ₁₁ , C ₁₂ C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₁₂	M ₁₃	C11, C12, C13, C14 C12, C13, C14, C15
M ₁₄	M ₁₅	C ₁₃ , C ₁₄ , C ₁₅ C ₁₄ , C ₁₅

The Macrocell

The MACH210 has two types of macrocell: output and buried. The output macrocells can be configured as either registered, latched, or combinatorial, with programmable polarity. The macrocell provides internal feedback whether configured with or without the flipflop. The registers can be configured as D-type or T-type, allowing for product-term optimization.

The flip-flops can individually select one of two clock/ gate pins, which are also available as data inputs. The registers are clocked on the LOW-to-HIGH transition of the clock signal. The latch holds its data when the gate input is HIGH, and is transparent when the gate input is LOW. The flip-flops can also be asynchronously initialized with the common asynchronous reset and preset product terms.

The buried macrocells are the same as the output macrocells if they are used for generating logic. In that case, the only thing that distinguishes them from the output macrocells is the fact that there is no I/O cell connection, and the signal is only used internally. The buried macrocell can also be configured as an input register or latch.

The I/O Cell

The I/O cell in the MACH210 consists of a three-state output buffer. The three-state buffer can be configured in one of three ways: always enabled, always disabled, or controlled by a product term. If product term control is chosen, one of two product terms may be used to provide the control. The two product terms that are available are common to all I/O cells in a PAL block.

These choices make it possible to use the macrocell as an output, an input, a bidirectional pin, or a three-state output for use in driving a bus.

PCI Compliance

The MACH210A-7/10 is fully compliant with the *PCI Local Bus Specification* published by the PCI Special Interest Group. The MACH210A-7/10's predictable timing ensures compliance with the PCI AC specifications independent of the design. On the other hand, in CPLD and FPGA architectures without predictable timing, PCI compliance is dependent upon routing and product term distribution.

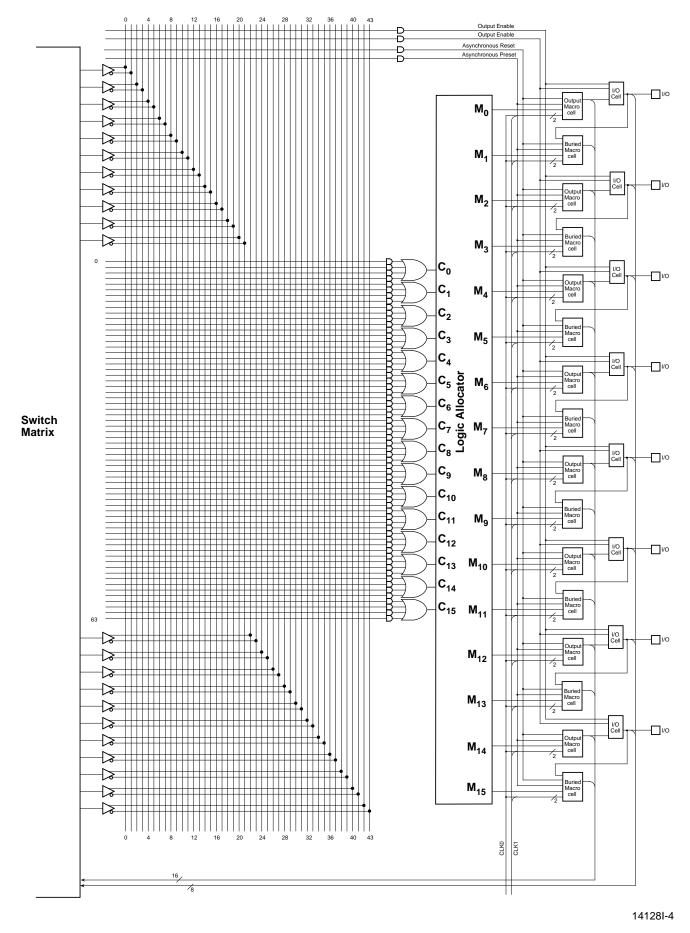


Figure 1. MACH210 PAL Block

ABSOLUTE MAXIMUM RATINGS

Storage Temperature $\ \dots \ -65^{\circ}\text{C}$ to $+150^{\circ}\text{C}$
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage with Respect to Ground $\dots -0.5 \text{ V}$ to +7.0 V
DC Input Voltage -0.5 V to Vcc + 0.5 V
DC Output or
I/O Pin Voltage $$ -0.5 V to V _{CC} + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current
$(T_A = 0^{\circ}C \text{ to } +70^{\circ}C) \dots 200 \text{ mA}$

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices

Temperature (T _A) Operating in Free Air	0°C to +70°C
Supply Voltage (Vcc) with Respect to Ground +4.75	V to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Voн	Output HIGH Voltage	IOH = -3.2 mA, VCC = Min VIN = VIH or VIL	2.4			V
Vol	Output LOW Voltage	I _{OL} = 16 mA, V _{CC} = Min V _{IN} = V _{IH} or V _{IL}			0.5	V
ViH	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
VIL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
Іін	Input HIGH Leakage Current	V _{IN} = 5.25 V, V _{CC} = Max (Note 2)			10	μΑ
lı∟	Input LOW Leakage Current	VIN = 0 V, Vcc = Max (Note 2)			-100	μΑ
Іоzн	Off-State Output Leakage Current HIGH	Vout = 5.25 V, Vcc = Max V _{IN} = V _{IH} or V _{IL} (Note 2)			10	μΑ
lozL	Off-State Output Leakage Current LOW	Vout = 0 V, Vcc = Max Vin = Vih or Vil (Note 2)			-100	μΑ
Isc	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30		-160	mA
Icc	Supply Current	V _{IN} = 0 V, Outputs Open (I _{OUT} = 0 mA) V _{CC} = 5.0 V, f = 25 MHz, T _A = 25°C (Note 4)		130		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_IH and I_{OZ}H).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.
- 4. This parameter is measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and capable of being loaded, enabled, and reset.

CAPACITANCE (Note 1)

Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
CIN	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	Vout = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges

Parameter Symbol	Parameter	r Description		Min	Max	Unit
t _{PD}	Input, I/O, or Feedback to Combinatorial Output			7.5	ns	
ts	Setup Time	e from Input, I/O or Feedback to Clock	D-Type	5.5		ns
			T-Type	6.5		ns
tн	Register D	ata Hold Time		0		ns
tco	Clock to O	utput			5	ns
tw∟	Clock Widt	th	LOW	3		ns
twn			HIGH	3		ns
		Fytograd Foodbook	D-Type	100		MHz
	Maximum	External Feedback	T-Type	91		MHz
fmax	Frequency	Internal Foodback (faur.)	D-Type	133		MHz
		Internal Feedback (fcnt)	T-Type	125		MHz
		No Feedback		166.7		MHz
t _{SL}	Setup Time	e from Input, I/O, or Feedback to Gate		5.5		ns
tHL	Latch Data	a Hold Time		0		ns
tgo	Gate to Ou	Gate to Output			6	ns
tgwL	Gate Width LOW		3		ns	
tPDL		or Feedback to Output Through nt Input or Output Latch			9.5	ns
tsır	Input Regis	ster Setup Time		2		ns
thir	Input Regis	ster Hold Time		2		ns
tico	Input Regis	ster Clock to Combinatorial Output			11	ns
tics	Input Regis	ster Clock to Output Register Setup	D-Type	9		ns
			T-Type	10		ns
twicl	Input Regis	ster Clock Width	LOW	3		ns
twich			HIGH	3		ns
fmaxir	Maximum Input Register Frequency		166.7		MHz	
tsıL	Input Latch	n Setup Time		2		ns
tHIL	Input Latch	n Hold Time		2		ns
tigo	Input Latch	n Gate to Combinatorial Output			12	ns
tigoL	Input Latch	n Gate to Output Through Transparent Output L	_atch		14	ns
t _{SLL}		e from Input, I/O, or Feedback Through nt Input Latch to Output Latch Gate		7.5		ns

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (continued)

Parameter		-7		
Symbol	Parameter Description	Min	Max	Unit
tigs	Input Latch Gate to Output Latch Setup	10		ns
twigL	Input Latch Gate Width LOW	3		ns
tPDLL	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches		11.5	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output		12	ns
tarw	Asynchronous Reset Width	8		ns
tarr	Asynchronous Reset Recovery Time	8		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		12	ns
tapw	Asynchronous Preset Width	8		ns
tapr	Asynchronous Preset Recovery Time	8		ns
tea	Input, I/O, or Feedback to Output Enable		7.5	ns
t _{ER}	Input, I/O, or Feedback to Output Disable		7.5	ns

^{1.} These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature $\ \dots \ -65^{\circ}\text{C}$ to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage with Respect to Ground $\dots -0.5 \text{ V}$ to +7.0 V
DC Input Voltage $-0.5~\text{V}$ to Vcc + 0.5 V
DC Output or
I/O Pin Voltage $$ $$ –0.5 V to V _{CC} + 0.5 V $$
Static Discharge Voltage 2001 V
Latchup Current ($T_A = 0$ °C to +70°C) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices

Supply Voltage (Vcc) with	in Free Air 0°C to +70°C
	Supply Voltage (Vcc) with Respect to Ground +4.75 V to +5.25

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Vон	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = Min$ $V_{IN} = V_{IH}$ or V_{IL}	2.4			V
Vol	Output LOW Voltage	I_{OL} = 16 mA, V_{CC} = Min V_{IN} = V_{IH} or V_{IL}			0.5	٧
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
VıL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
I _{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25 \text{ V}, V_{CC} = \text{Max (Note 2)}$			10	μΑ
I _{IL}	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}, V_{CC} = \text{Max (Note 2)}$			-100	μΑ
Іоzн	Off-State Output Leakage Current HIGH	V_{OUT} = 5.25 V, V_{CC} = Max V_{IN} = V_{IH} or V_{IL} (Note 2)			10	μА
l _{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			-100	μА
I _{SC}	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30		-160	mA
Icc	Supply Current (Typical)	$V_{CC} = 5V$, $T_A = 25$ °C, $f = 25$ MHz (Note 4)		135		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of IIL and IOZL (or IIH and IOZH).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

CAPACITANCE (Note 1)

Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter					-1	0	-13	2	
Symbol	Parameter I	Description			Min	Max	Min	Max	Unit
t _{PD}	Input, I/O, or (Note 3)	r Feedback to Combii	natorial Output			10		12	ns
,		from Input, I/O,		D-Type	6.5		7		ns
ts ts	or Feedback	to Clock		T-Type	7.5		8		ns
t _H	Register Dat	ta Hold Time		•	0		0		ns
t _{CO}	Clock to Out	tput (Note 3)				6		8	ns
tw∟	Clock			LOW	5		6		ns
t _{WH}	Width			HIGH	5		6		ns
				D-Type	80		66.7		MHz
	 Maximum	External Feedback	1/(ts + tco)	T-Type	74		62.5		MHz
f _{MAX}	Frequency			D-Type	100		83.3		MHz
	(Note 1)	Internal Feedback (fCNT)	T-Type	91		76.9		MHz
		No Feedback	1/(ts + t _H)		100		83.3		MHz
t _{SL}	Setup Time	Setup Time from Input, I/O, or Feedback to Gate			6.5		7		ns
t _{HL}	i .	Latch Data Hold Time			0		0		ns
tgo		Gate to Output (Note 3)				7		10	ns
t _{GWL}		Gate Width LOW			5		6		ns
t _{PDL}		Input, I/O, or Feedback to Output Through							
4 DE	Transparent Input or Output Latch			12		14	ns		
tsir	Input Regist	er Setup Time			2		2		ns
t _{HIR}	Input Regist	er Hold Time			2		2		ns
t _{ICO}	Input Regist	er Clock to Combinat	orial Output			13		15	ns
t _{ICS}	Input Regist	er Clock to Output Re	egister Setup	D-Type	10		12		ns
				T-Type	11		13		ns
twicl	Input Regist	er		LOW	5		6		ns
twich	Clock Width			HIGH	5		6		ns
f _{MAXIR}	Maximum In	put Register Frequer	ncy 1/(twicL +	twich)	100		83.3		MHz
tsıL	Input Latch Setup Time		2		2		ns		
t _{HIL}	Input Latch I	Input Latch Hold Time		2		2		ns	
tigo	Input Latch Gate to Combinatorial Output			14		17	ns		
tigol	Input Latch Gate to Output Through Transparent Output Latch			_	16		19	ns	
t _{SLL}	Setup Time from Input, I/O, or Feedback Through Transparent Input Latch to Output Latch Gate			8.5		9		ns	
t _{IGS}	Input Latch	Gate to Output Latch	Setup		11		13		ns

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2) (continued)

Parameter	r		0	-1	2	
Symbol	Parameter Description	Min	Max	Min	Max	Unit
twigL	Input Latch Gate Width LOW	5		6		ns
t _{PDLL}	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches		14		16	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output		25		16	ns
t _{ARW}	Asynchronous Reset Width (Note 1)	10		12		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	10		8		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		15		16	ns
t _{APW}	Asynchronous Preset Width (Note 1)	10		12		ns
tapr	Asynchronous Preset Recovery Time (Note 1)	10		8		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		10		12	ns
t _{ER}	Input, I/O, or Feedback to Output Disable (Note 3)		10		12	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied –55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage0.5 V to Vcc + 0.5 V
DC Output or
I/O Pin Voltage -0.5 V to V_{CC} + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current ($T_A = 0^{\circ}C$ to $+70^{\circ}C$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

INDUSTRIAL OPERATING RANGES

Temperature (T _A) Operating	
in Free Air	-40°C to +85°C
Supply Voltage (V _{CC}) with	
Respect to Ground	+4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Vон	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = Min$ $V_{IN} = V_{IH}$ or V_{IL}	2.4			V
Vol	Output LOW Voltage	I_{OL} = 16 mA, V_{CC} = Min V_{IN} = V_{IH} or V_{IL}			0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
VıL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
I _{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25 \text{ V}, V_{CC} = \text{Max (Note 2)}$			10	μΑ
I _{IL}	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}, V_{CC} = \text{Max (Note 2)}$			-100	μΑ
l _{оzн}	Off-State Output Leakage Current HIGH	V_{OUT} = 5.25 V, V_{CC} = Max V_{IN} = V_{IH} or V_{IL} (Note 2)			10	μА
l _{ozL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			-100	μА
I _{sc}	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30		-160	mA
Icc	Supply Current (Typical)	$V_{CC} = 5V$, $T_A = 25$ °C, $f = 25$ MHz (Note 4)		135		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. $V_{OUT} = 0.5 \text{ V}$ has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

CAPACITANCE (Note 1)

Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter					-1:	2	-1-	4	
Symbol	Parameter I	Description			Min	Max	Min	Max	Unit
t _{PD}	Input, I/O, or (Note 3)	r Feedback to Combin	natorial Output			12		14.5	ns
	Setup Time	from Input, I/O,		D-Type	8		8.5		ns
ts ts	or Feedback	to Clock		T-Type	9		10		ns
t _H	Register Dat	ta Hold Time		•	0		0		ns
t _{co}	Clock to Out	tput (Note 3)				7.5		10	ns
tw∟	Clock			LOW	6		7.5		ns
t _{WH}	Width			HIGH	6		7.5		ns
				D-Type	64		53		MHz
	Maximum	External Feedback	1/(ts + tco)	T-Type	59		50		MHz
f _{MAX}	Frequency			D-Type	80		61.5		MHz
	(Note 1)	Internal Feedback (fcnt)	T-Type	72.5		57		MHz
		No Feedback	1/(ts + t _H)		80		66.5		MHz
t _{SL}	Setup Time	Setup Time from Input, I/O, or Feedback to Gate			8		8.5		ns
thL	Latch Data Hold Time			0		0		ns	
t _{GO}	Gate to Output (Note 3)				8.5		12	ns	
t _{GWL}	Gate Width LOW			6		7.5		ns	
t _{PDL}	Input, I/O, or Feedback to Output Through								
		Transparent Input or Output Latch			14.5	0.5	17	ns	
tsir		er Setup Time			2.5		2.5		ns
thir	· •	er Hold Time			3		3		ns
t _{ICO}		er Clock to Combinat	-			16		18	ns
t _{ICS}	Input Regist	er Clock to Output Re	egister Setup	D-Type	12		14.5		ns
				T-Type	13		16		ns
twicl	Input Regist			LOW	6		7.5		ns
twich	Clock Width			HIGH	6		7.5		ns
f MAXIR	Maximum In	put Register Frequer	ncy 1/(twicL +	twicн)	80		66.5		MHz
tsıL	Input Latch Setup Time		2.5		2.5		ns		
tHIL	Input Latch Hold Time		3		3		ns		
tigo	Input Latch Gate to Combinatorial Output			17		20.5	ns		
tigoL	Input Latch Gate to Output Through Transparent Output Latch				19.5		23	ns	
tsll	Setup Time from Input, I/O, or Feedback Through Transparent Input Latch to Output Latch Gate			10.5		11		ns	
t _{IGS}	· ·	Gate to Output Latch			13.5		16		ns

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2) (continued)

Parameter	arameter		2	-14		
Symbol	Parameter Description		Max	Min	Max	Unit
twigL	Input Latch Gate Width LOW	6		7.5		ns
t _{PDLL}	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches		17		19.5	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output		19.5		19.5	ns
t _{ARW}	Asynchronous Reset Width (Note 1)	12		14.5		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	12		10		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		18		19.5	ns
t _{APW}	Asynchronous Preset Width (Note 1)	12		14.5		ns
tapr	Asynchronous Preset Recovery Time (Note 1)	12		10		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		12		14.5	ns
t _{ER}	Input, I/O, or Feedback to Output Disable (Note 3)		12		14.5	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature $\ \dots \ -65^{\circ}C$ to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage with Respect to Ground $\dots -0.5 \text{ V}$ to +7.0 V
DC Input Voltage $-0.5~\text{V}$ to Vcc + 0.5 V
DC Output or I/O Pin Voltage0.5 V to V _{CC} + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current ($T_A = 0$ °C to +70°C) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices

Temperature (T _A) Operating in Free Air 0°C	to +70°C
Supply Voltage (Vcc) with Respect to Ground +4.75 V to	+5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
V _{он}	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = Min$ $V_{IN} = V_{IH}$ or V_{IL}		2.4		V
Vol	Output LOW Voltage	$I_{OL} = 16$ mA, $V_{CC} = Min$ $V_{IN} = V_{IH}$ or V_{IL}			0.5	٧
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			>
VıL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	>
I _{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25 \text{ V}, V_{CC} = \text{Max (Note 2)}$			10	μΑ
I _{IL}	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}, V_{CC} = \text{Max (Note 2)}$			-10	μΑ
Іохн	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			10	μΑ
lozL	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			-10	μΑ
Isc	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}, V_{CC} = \text{Max (Note 3)}$		-30	-160	mA
Icc	Supply Current (Typical)	V _{CC} = 5V, T _A = 25°C, f = 25 MHz (Note 4)		120		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. $V_{OUT} = 0.5 \text{ V}$ has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

CAPACITANCE (Note 1)

Parameter Symbol	Parameter Description	Test Condition	ns	Тур	Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter						-1:	2	-1		-2	0	
Symbol	Parameter I	Description				Min	Max	Min	Max	Min	Max	Unit
t _{PD}	Input, I/O, or (Note 3)	Feedback to Combi	natori	ial Output			12		15		20	ns
	Setup Time	from Input, I/O,			D-type	7		10		13		ns
ts	or Feedback	to Clock			T-type	8		11		14		ns
t⊢	Register Dat	Register Data Hold Time			0		0		0		ns	
tco	Clock to Out	tput (Note 3)					8		10		12	ns
tw∟	Clock				LOW	6		6		8		ns
twн	Width				HIGH	6		6		8		ns
		Evtornal Foodbook	External Feedback 1/(ts + tcd		D-type	66.7		50		40		MHz
	Maximum	External Feedback			T-type	62.5		47.6		38.5		MHz
f _{MAX}	Frequency				D-type	83.3		66.6		50		MHz
	(Note 1)	Internal Feedback (fcnt)		T-type	76.9		62.5		47.6		MHz
		No Feedback 1/(t _{WL} + t _{WH})			83.3		83.3		62.5		MHz	
tsL	Setup Time from Input, I/O, or Feedback to Gate			7		10		13		ns		
tHL	Latch Data Hold Time			0		0		0		ns		
tgo	Gate to Outp	out (Note 3)					10		11		12	ns
t _{GWL}	Gate Width I	LOW				6		6		8		ns
t _{PDL}	Input, I/O, or	Feedback to Output	Thro	ough								
	Transparent	Input or Output Latel	h				14		17		22	ns
tsir	Input Regist	er Setup Time				2		2		2		ns
t _{HIR}	Input Regist	er Hold Time				2		2.5		3		ns
tico	Input Regist	er Clock to Combinat	torial	Output			15		18		23	ns
tics	Input Regist	er Clock to Output Re	egiste	er Setup	D-type	12		15		20		ns
					T-type	13		16		21		ns
twicl	Input Regist	er			LOW	6		6		8		ns
twich	Clock Width				HIGH	6		6		8		ns
f _{MAXIR}	Maximum In	put Register Frequer	псу	1/(twick + twick	сн)	83.3		83.3		62.5		MHz
t _{SIL}	Input Latch	Setup Time				2		2		2		ns
thiL	Input Latch I	Hold Time				2		2.5		3		ns
tigo	Input Latch (Gate to Combinatoria	l Out	put			17		20		25	ns
tigoL	Input Latch Gate to Output Through Transparent Output Latch				19		22		27	ns		
t _{SLL}		from Input, I/O, or Fe Input Latch to Outpu				9		12		15		ns
tigs	•	Gate to Output Latch				13		16		21		ns
	•	'		•								

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2) (continued)

Parameter		-1	2	-1	5	-2	0	
Symbol	Parameter Description		Max	Min	Max	Min	Max	Unit
twigL	Input Latch Gate Width LOW	6		6		8		ns
t _{PDLL}	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches		16		19		24	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output		16		20		25	ns
t _{ARW}	Asynchronous Reset Width (Note 1)	12		15		20		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	8		10		15		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		16		20		25	ns
tapw	Asynchronous Preset Width (Note 1)	12		15		20		ns
tapr	Asynchronous Preset Recovery Time (Note 1)	8		10		15		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		12		15		20	ns
ter	Input, I/O, or Feedback to Output Disable (Note 3)		12		15		20	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature $\ \dots \ -65^{\circ}C$ to $+150^{\circ}C$
Ambient Temperature With Power Applied55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage –0.5 V to V _{CC} + 0.5 V
DC Output or I/O
Pin Voltage
Static Discharge Voltage 2001 V
Latchup Current
$(T_A = -40^{\circ}C \text{ to } +85^{\circ}C) \dots 200 \text{ mA}$

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

INDUSTRIAL OPERATING RANGES

Ambient Temperature (T_A)
Operating in Free Air -40°C to +85°C
Supply Voltage (V_{CC})
with Respect to Ground +4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over INDUSTRIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Voн	Output HIGH Voltage	$I_{OH} = -3.2 \text{ mA}, V_{CC} = \text{Min}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	2.4			V
V _{OL}	Output LOW Voltage	$I_{OL} = 16 \text{ mA}, V_{CC} = \text{Min}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
V _{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
I _{IH}	Input HIGH Leakage Current	V _{IN} = 5.25 V, V _{CC} = Max (Note 2)			10	μΑ
I₁∟	Input LOW Leakage Current	V _{IN} = 0 V, V _{CC} = Max (Note 2)			-10	μΑ
l _{OZH}	Off-State Output Leakage Current HIGH	V_{OUT} = 5.25 V, V_{CC} = Max V_{IN} = V_{IH} or V_{IL} (Note 2)			10	μА
l _{OZL}	Off-State Output Leakage Current LOW	V _{OUT} = 0 V, V _{CC} = Max V _{IN} = V _{IH} or V _{IL} (Note 2)			-10	μΑ
I _{SC}	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30		-160	mA
Icc	Supply Current (Typical)	V _{CC} = 5 V, T _A = 25°C, f = 25 MHz (Note 4)		120		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time. Duration of the short-circuit should not exceed one second. $V_{OUT} = 0.5 \text{ V}$ has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

CAPACITANCE (Note 1)

Parameter Symbol	Parameter Description	Test Conditio	ns	Тур	Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over INDUSTRIAL operating ranges (Note 2)

Parameter					-1	4	-1	8	-2	4	
Symbol	Parameter I	Description			Min	Max	Min	Max	Min	Max	Unit
t _{PD}	Input, I/O, or (Note 3)	r Feedback to Combi	natorial Output			14.5		18		24	ns
4-		from Input, I/O,		D-type	8.5		12		16		ns
ts	or Feedback	to Clock		T-type	10		13.5		17		ns
t _H	Register Dat	ta Hold Time			0		0		0		ns
tco	Clock to Out	tput (Note 3)				10		12		14.5	ns
t _{WL}	Clock			LOW	7.5		7.5		10		ns
twH	Width	T	1	HIGH D-type	7.5		7.5		10		ns
		External Feedback	kternal Feedback 1/(t _S + t _{CO})		53		40		32		MHz
	Maximum		17(10 1 100)	T-type	50		38		30.5		MHz
f_{MAX}	Frequency			D-type	61.5		53		38		MHz
	(Note 1)	Internal Feedback (CNT)	T-type	57		44		34.5		MHz
		No Feedback 1/(t _{WL} + t _{WH})			66.5		66.5		50		MHz
t _{SL}	Setup Time from Input, I/O, or Feedback to Gate			8.5		12		16		ns	
t⊢∟	Latch Data Hold Time			0		0		0		ns	
t _{GO}	Gate to Outp	out (Note 3)				12		13.5		14.5	ns
t _{GWL}	Gate Width I	Gate Width LOW		7.5		7.5		10		ns	
t _{PDL}	Input, I/O, or Feedback to Output Through Transparent Input or Output Latch			17		20.5		26.5	ns		
t _{SIR}	Input Regist	er Setup Time			2.5		2.5		2.5		ns
t _{HIR}	Input Regist	er Hold Time			3		3.5		4		ns
t _{ICO}	Input Regist	er Clock to Combinat	orial Output			18		22		28	ns
t _{ICS}	Input Regist	er Clock to Output Re	egister Setup	D-type	14.5		18		24		ns
				T-type	16		19.5		25.5		ns
twicL	Input Regist	er		LOW	7.5		7.5		10		ns
twich	Clock Width			HIGH	7.5		7.5		10		ns
f _{MAXIR}	Maximum In	put Register Frequer	ncy 1/(t _{WICL} + t	wic i)	66.5		66.5		50		MHz
t _{SIL}	Input Latch	Setup Time	•		2.5		2.5		2.5		ns
t _{HIL}	Input Latch I	Hold Time			3		3.5		4		ns
tigo	Input Latch (Gate to Combinatoria	l Output			20.5		24		30	ns
t _{IGOL}	Input Latch (Output Latch	Gate to Output Throu า	gh Transparent			23		26.5		32.5	ns
t _{SLL}		from Input, I/O, or Fe Input Latch to Outpu		1	11		14.5		18		ns
t _{IGS}	Input Latch (Gate to Output Latch	Setup		16		19.5		25.5		ns
twigL	Input Latch	Gate Width LOW			7.5		7.5		10		ns
t _{PDLL}		r Feedback to Output utput Latches	Through Transp	parent		19.5		23		29	ns

SWITCHING CHARACTERISTICS over INDUSTRIAL operating ranges (Note 2) (continued)

Parameter		-1	-14		-18		4	
Symbol	Parameter Description		Max	Min	Max	Min	Max	Unit
t _{AR}	Asynchronous Reset to Registered or Latched Output		19.5		24		30	ns
t _{ARW}	Asynchronous Reset Width (Note 1)			18		24		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)			12		18		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		19.5		24		30	ns
t _{APW}	Asynchronous Preset Width (Note 1)	14.5		18		24		ns
t _{APR}	Asynchronous Preset Recovery Time (Note 1)	10		12		18		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		14.5		18		24	ns
t _{ER}	Input, I/O, or Feedback to Output Disable (Note 3)		14.5		18		24	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature –65°C to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage0.5 V to Vcc + 0.5 V
DC Output or
I/O Pin Voltage0.5 V to V _{CC} + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current ($T_A = 0$ °C to +70°C) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices

Temperature (T _A) Operating in Free Air 0°	C to +70°C
Supply Voltage (Vcc) with Respect to Ground +4.75 V	′ to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Voн	Output HIGH Voltage	$I_{OH} = -3.2 \text{ mA}, V_{CC} = Min$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	2.4			V
VoL	Output LOW Voltage	$I_{OL} = 16 \text{ mA}, V_{CC} = Min$ $V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
V _{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
Іін	Input HIGH Leakage Current	$V_{IN} = 5.25 \text{ V}, V_{CC} = \text{Max (Note 2)}$			10	μΑ
lı∟	Input LOW Leakage Current	V _{IN} = 0 V, V _{CC} = Max (Note 2)			-100	μΑ
I _{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			10	μΑ
lozL	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			-100	μΑ
Isc	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}, V_{CC} = \text{Max (Note 3)}$	-30		-160	mA
Icc	Supply Current (Typical)	V _{CC} = 5 V, T _A = 25°C, f = 25 MHz (Note 4)		45		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. $V_{OUT} = 0.5 \text{ V}$ has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

CAPACITANCE (Note 1)

Parameter Symbol	Parameter Description	Test Condition	ns	Тур	Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter				-12	2	1
Symbol	Parameter I	Description		Min	Max	Unit
t _{PD}	Input, I/O, or	r Feedback to Combinatorial Output		12	ns	
	Setup Time	from Input, I/O,	D-type	12		ns
ts	or Feedback		T-type	13		ns
tн	Register Da	ta Hold Time		0		ns
t _{CO}	Clock to Out	Clock to Output				ns
tw∟	Clock		LOW	6		ns
tw⊢	Width		HIGH	6		ns
	External Faadlaad	D-type	55.6		MHz	
	Maximum	External Feedback	T-type	52.6		MHz
f_{MAX}	(Note 1) Internal Fed	Internal Foodback (form)	D-type	83.3		MHz
		Internal Feedback (fcnt)	T-type	76.9		MHz
		No Feedback		83.3		MHz
t _{SL}	Setup Time	from Input, I/O, or Feedback to Gate		12		ns
t _H ∟	Latch Data I	Latch Data Hold Time				ns
tgo	Gate to Output				7	ns
t _{GWL}	Gate Width LOW			6		ns
tpdL	Input, I/O, o	r Feedback to Output Through				
	Transparent	Input or Output Latch			14	ns
tsır	Input Regist	er Setup Time		2		ns
t _{HIR}	Input Regist	er Hold Time		2.5		ns
tico	Input Regist	er Clock to Combinatorial Output			17	ns
tics	Input Regist	er Clock to Output Register Setup	D-type	15		ns
			T-type	16		ns
twicl	Input Regist	er	LOW	6		ns
twich	Clock Width		HIGH	6		ns
f _{MAXIR}	Maximum In	put Register Frequency		83.3		MHz
t _{SIL}	Input Latch	Setup Time		2		ns
t _{HIL}	Input Latch	Hold Time		2.5		ns
t _{IGO}	Input Latch	Gate to Combinatorial Output			19	ns
tigol	Input Latch	Gate to Output Through Transparent				
	Output Latch				20	ns
tsll		from Input, I/O, or Feedback Through				
		Input Latch to Output Latch Gate		13		ns
tigs	Input Latch	Gate to Output Latch Setup		16		ns

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2) (continued)

Parameter		-1	-12	
Symbol	Parameter Description	Min	Max	Unit
twigL	Input Latch Gate Width LOW	6		ns
t _{PDLL}	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches		18	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output		24	ns
t _{ARW}	Asynchronous Reset Width (Note 1)	19		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	19		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		24	ns
t _{APW}	Asynchronous Preset Width (Note 1)	19		ns
t _{APR}	Asynchronous Preset Recovery Time (Note 1)	19		ns
t _{EA}	Input, I/O, or Feedback to Output Enable		12	ns
t_{ER}	Input, I/O, or Feedback to Output Disable		12	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature65°C to +150°C
Ambient Temperature with Power Applied55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage0.5 V to Vcc + 0.5 V
DC Output or
I/O Pin Voltage0.5 V to V _{CC} + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current ($T_A = 0^{\circ}C$ to $+70^{\circ}C$) 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

OPERATING RANGES

Commercial (C) Devices

Temperature (T _A) Operating in Free Air	0°C to +70°C
Supply Voltage (Vcc) with Respect to Ground +4.75	V to +5.25 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over COMMERCIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Vон	Output HIGH Voltage	$I_{OH} = -3.2$ mA, $V_{CC} = Min$ $V_{IN} = V_{IH}$ or V_{IL}	2.4			V
VoL	Output LOW Voltage	$I_{OL} = 16 \text{ mA}, V_{CC} = \text{Min}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
VıL	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
I _{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25 \text{ V}, V_{CC} = \text{Max (Note 2)}$			10	μΑ
I _{IL}	Input LOW Leakage Current	$V_{IN} = 0 \text{ V}, V_{CC} = \text{Max (Note 2)}$			-100	μA
l _{ozh}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			10	μΑ
lozL	Off-State Output Leakage Current LOW	$V_{OUT} = 0 \text{ V}, V_{CC} = \text{Max}$ $V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 2)}$			-100	μΑ
I _{sc}	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30		-160	mA
Icc	Supply Current (Typical)	V _{CC} = 5V, T _A = 25°C, f = 25 MHz (Note 4)		45		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time and duration of the short-circuit should not exceed one second. Vout = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

CAPACITANCE (Note 1)

Parameter Symbol	Parameter Description	Test Conditions		Тур	Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2)

Parameter						-1	5	-20	0	
Symbol	Parameter Description				Min	Max	Min	Max	Unit	
t _{PD}	Input, I/O, or (Note 3)	r Feedback to Combi	natoria	al Output			15		20	ns
,	Setup Time	Setup Time from Input, I/O,			D-type	13		17		ns
ts	or Feedback	to Clock			T-type	14		18		ns
t _H	Register Dat	ta Hold Time			•	0		0		ns
t _{CO}	Clock to Out	tput (Note 3)					7		8	ns
tw∟	Clock				LOW	6		8		ns
t _{WH}	Width				HIGH	6		8		ns
			l		D-type	50		40		MHz
	Maximum	External Feedback	1/(ts	+ tco)	T-type	47.6		38.4		MHz
f _{MAX}	Frequency		•		D-type	58.8		45.4		MHz
	(Note 1) Internal Feedback	(fCNT)		T-type	55.5		43.4		MHz	
					D-type	76.9		58.8		MHz
		No Feedback	1/(ts	+ t _H)	T-type	71.4		55.5		MHz
t _{SL}	Setup Time	from Input, I/O, or Fe	edbad	k to Gate		13		17		ns
thL	Latch Data H	Hold Time				0		0		ns
t _{GO}	Gate to Outp	out (Note 3)					8		8	ns
t _{GWL}	Gate Width	LOW				6		8		ns
t _{PDL}		r Feedback to Output Input or Output Late		ıgh			17		22	ns
tsir	Input Regist	er Setup Time				2		2		ns
t _{HIR}	Input Regist	er Hold Time				2.5		3		ns
t _{ICO}	Input Regist	er Clock to Combinat	torial C	Dutput			18		23	ns
t _{ICS}	Input Regist	er Clock to Output Re	egiste	r Setup	D-type	17		22		ns
					T-type	18		23		ns
twicl	Input Regist	er			LOW	6		8		ns
twich	Clock Width				HIGH	6		8		ns
f _{MAXIR}	Maximum In	put Register Frequer	ncy	1/(twick + twi	сн)	83.3		62.5		MHz
tsıL	Input Latch	Setup Time				2		2		ns
t _{HIL}	Input Latch I	t Latch Hold Time		2.5		3		ns		
tigo	Input Latch (Gate to Combinatoria	al Outp	out			20		25	ns
tigol	Input Latch (Output Latch	Gate to Output Throu า	igh Tra	ansparent			22		27	ns
t _{SLL}		from Input, I/O, or Fe Input Latch to Outpu				15		19		ns
t _{iGS}		Gate to Output Latch				18		23		ns

SWITCHING CHARACTERISTICS over COMMERCIAL operating ranges (Note 2) (continued)

Parameter	ameter		-15		-20	
Symbol	Parameter Description	Min	Max	Min	Max	Unit
twigL	Input Latch Gate Width LOW	6		8		ns
t _{PDLL}	Input, I/O, or Feedback to Output Through Transparent Input and Output Latches		19		24	ns
t _{AR}	Asynchronous Reset to Registered or Latched Output		25		30	ns
t _{ARW}	Asynchronous Reset Width (Note 1)	20		25		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	20		25		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		25		30	ns
tapw	Asynchronous Preset Width (Note 1)	20		25		ns
tapr	Asynchronous Preset Recovery Time (Note 1)	20		25		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		15		20	ns
ter	Input, I/O, or Feedback to Output Disable (Note 3)		15		20	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature65°C to +150°C
Ambient Temperature With Power Applied55°C to +125°C
Supply Voltage with Respect to Ground0.5 V to +7.0 V
DC Input Voltage –0.5 V to V _{CC} + 0.5 V
DC Output or I/O Pin Voltage0.5 V to V_{CC} + 0.5 V
Static Discharge Voltage 2001 V
Latchup Current $(T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$ 200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability. Programming conditions may differ.

INDUSTRIAL OPERATING RANGES

Ambient Temperature (T_A)
Operating in Free Air -40°C to +85°C
Supply Voltage (V_{CC})
with Respect to Ground +4.5 V to +5.5 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over INDUSTRIAL operating ranges unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min	Тур	Max	Unit
Vон	Output HIGH Voltage	I_{OH} = -3.2 mA, V_{CC} = Min V_{IN} = V_{IH} or V_{IL}	2.4			V
VoL	Output LOW Voltage	$I_{OL} = 16 \text{ mA}, V_{CC} = \text{Min}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 1)	2.0			V
V _{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 1)			0.8	V
I _{IH}	Input HIGH Leakage Current	V _{IN} = 5.25 V, V _{CC} = Max (Note 2)			10	μΑ
l₁∟	Input LOW Leakage Current	V _{IN} = 0 V, V _{CC} = Max (Note 2)			-100	μΑ
lozh	Off-State Output Leakage Current HIGH	V_{OUT} = 5.25 V, V_{CC} = Max V_{IN} = V_{IH} or V_{IL} (Note 2)			10	μА
l _{OZL}	Off-State Output Leakage Current LOW	V _{OUT} = 0 V, V _{CC} = Max V _{IN} = V _{IH} or V _{IL} (Note 2)			-100	μА
Isc	Output Short-Circuit Current	V _{OUT} = 0.5 V, V _{CC} = Max (Note 3)	-30		-160	mA
Icc	Supply Current (Typical)	V _{CC} = 5 V, T _A = 25°C, f = 25 MHz (Note 4)		45		mA

- 1. These are absolute values with respect to device ground and all overshoots due to system and/or tester noise are included.
- 2. I/O pin leakage is the worst case of I_{IL} and I_{OZL} (or I_{IH} and I_{OZH}).
- 3. Not more than one output should be shorted at a time. Duration of the short-circuit should not exceed one second. V_{OUT} = 0.5 V has been chosen to avoid test problems caused by tester ground degradation.
- 4. Measured with a 16-bit up/down counter pattern. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

CAPACITANCE (Note 1)

Parameter Symbol	Parameter Description	Test Condition	Test Conditions		Unit
C _{IN}	Input Capacitance	V _{IN} = 2.0 V	$V_{CC} = 5.0 \text{ V}, T_A = 25^{\circ}\text{C},$	6	pF
Соит	Output Capacitance	V _{OUT} = 2.0 V	f = 1 MHz	8	pF

SWITCHING CHARACTERISTICS over INDUSTRIAL operating ranges (Note 2)

Parameter					-1	8	-2	4	
Symbol	Parameter I	Description			Min	Max	Min	Max	Unit
t _{PD}	Input, I/O, or Feedback to Combinatorial Output (Note 3)					18		24	ns
4-		Setup Time from Input, I/O, D-type					20.5		ns
ts	or Feedback	k to Clock		T-type	17		22		ns
tн	Register Da	ta Hold Time			0		0		ns
tco	Clock to Out	tput (Note 3)				8.5		10	ns
t _{WL}	Clock			LOW	7.5		10		ns
t _{WH}	Width	1	1	HIGH	7.5		10		ns
		External Feedback	1/(t _S + t _{CO})	D-type	40		32		MHz
	Maximum		1/(IS + ICO)	T-type	38		30.5		MHz
f_{MAX}	Frequency			D-type	47		36		MHz
	(Note 1)	Internal Feedback (CNT)	T-type	44		34.5		MHz
		No Foodback		D-type	61.5		47		MHz
		No Feedback	1/(t _S + t _H)	T-type	57		47		MHz
t _{SL}	Setup Time	Setup Time from Input, I/O, or Feedback to Gate					20.5		ns
t _{HL}	Latch Data I	Hold Time			0		0		ns
t _{GO}	Gate to Out	Gate to Output (Note 3)				10		10	ns
t _{GWL}	Gate Width	Gate Width LOW			7.5		10		ns
t _{PDL}		Input, I/O, or Feedback to Output Through Transparent Input or Output Latch				20.5		26.5	ns
t _{SIR}	Input Regist	er Setup Time			2.5		2.5		ns
t _{HIR}		er Hold Time			3.5		4		ns
t _{ICO}	Input Regist	er Clock to Combinat	orial Output			22		28	ns
tics	Input Regist	er Clock to Output Re	egister Setup	D-type	20.5		26.5		ns
				T-type	22		28		ns
twick	Input Regist	er		LOW	7.5		10		ns
twich	Clock Width			HIGH	7.5		10		ns
f _{MAXIR}	Maximum In	put Register Frequer	ncy 1/(t _{WICL} +	twich)	66.5		50		MHz
t _{SIL}	Input Latch	Setup Time	•		2.5		2.5		ns
t _{HIL}	Input Latch I	Hold Time			3.5		4		ns
t _{IGO}	Input Latch	Gate to Combinatoria	l Output			24		30	ns
tigoL	Input Latch (Output Latch	Input Latch Gate to Output Through Transparent				26.5		32.5	ns
t _{SLL}		from Input, I/O, or Fe t Input Latch to Outpu		ŋh	18		23		ns
t _{iGS}	Input Latch	Gate to Output Latch	Setup		22		28		ns
twigL	Input Latch	Gate Width LOW			7.5		10		ns
t _{PDLL}		r Feedback to Output utput Latches	Through Trans	sparent		23		29	ns

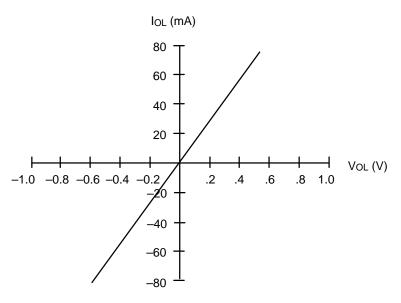
SWITCHING CHARACTERISTICS over INDUSTRIAL operating ranges (Note 2) (continued)

Parameter		-18		-24		
Symbol	Parameter Description	Min	Max	Min	Max	Unit
t _{AR}	Asynchronous Reset to Registered or Latched Output		30		36	ns
t _{ARW}	Asynchronous Reset Width (Note 1)	24		30		ns
t _{ARR}	Asynchronous Reset Recovery Time (Note 1)	24		30		ns
t _{AP}	Asynchronous Preset to Registered or Latched Output		30		36	ns
t _{APW}	Asynchronous Preset Width (Note 1)	24		30		ns
t _{APR}	Asynchronous Preset Recovery Time (Note 1)	24		30		ns
t _{EA}	Input, I/O, or Feedback to Output Enable (Note 3)		18		24	ns
t _{ER}	Input, I/O, or Feedback to Output Disable (Note 3)		18		24	ns

- 1. These parameters are not 100% tested, but are evaluated at initial characterization and at any time the design is modified where capacitance may be affected.
- 2. See Switching Test Circuit, for test conditions.
- 3. Parameters measured with 16 outputs switching.

TYPICAL CURRENT VS. VOLTAGE (I-V) CHARACTERISTICS

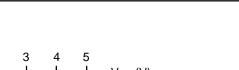
 $V_{CC} = 5.0 \text{ V}, T_{A} = 25^{\circ}\text{C}$

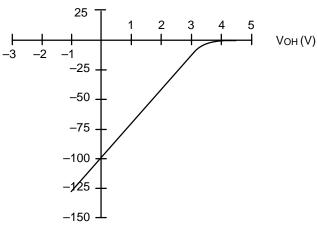


Output, LOW

Iон (mA)

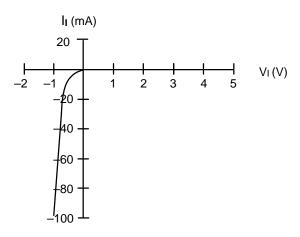
Output, HIGH





141281-6

14128I-5

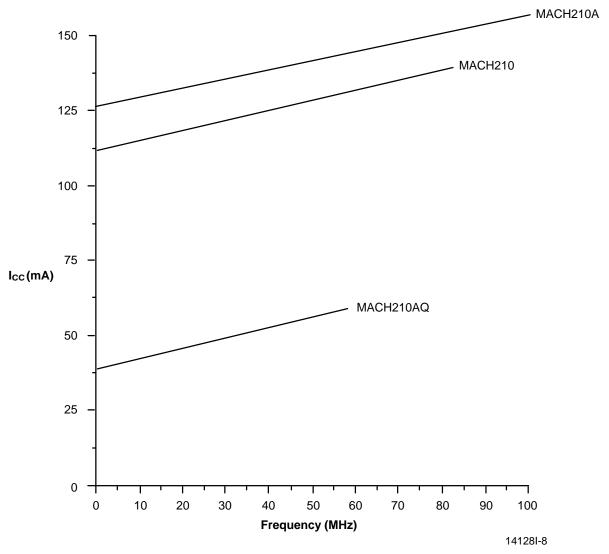


141281-7

Input

TYPICAL Icc CHARACTERISTICS

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$



The selected "typical" pattern is a 16-bit up/down counter. This pattern is programmed in each PAL block and is capable of being loaded, enabled, and reset.

Maximum frequency shown uses internal feedback and a D-type register.

TYPICAL THERMAL CHARACTERISTICS

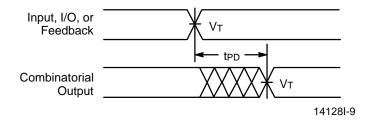
Measured at 25°C ambient. These parameters are not tested.

Parameter	Parameter		T		
Symbol	Parameter Description		TQFP	PLCC	Unit
θјс	Thermal impedance, junction to case		11.3	15	°C/W
θ_{ja}	Thermal impedance, junction to ambient		41	40	°C/W
θjma	Thermal impedance, junction to	200 lfpm air	35	36	°C/W
	ambient with air flow	400 Ifpm air	33.7	33	°C/W
		600 Ifpm air	32.6	31	°C/W
		800 Ifpm air	32	29	°C/W

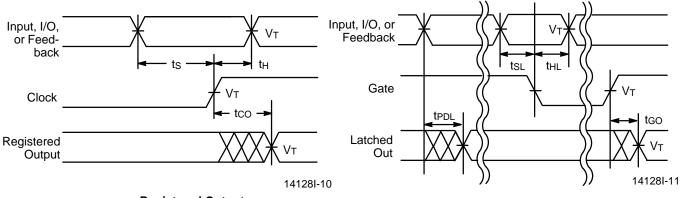
Plastic θ jc Considerations

The data listed for plastic θ jc are for reference only and are not recommended for use in calculating junction temperatures. The heat-flow paths in plastic-encapsulated devices are complex, making the θ jc measurement relative to a specific location on the package surface. Tests indicate this measurement reference point is directly below the die-attach area on the bottom center of the package. Furthermore, θ jc tests on packages are performed in a constant-temperature bath, keeping the package surface at a constant temperature. Therefore, the measurements can only be used in a similar environment.

SWITCHING WAVEFORMS

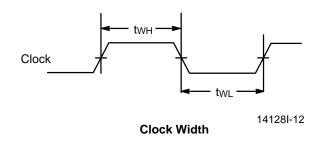


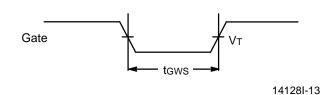
Combinatorial Output



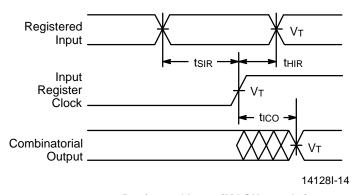
Registered Output

Latched Output (MACH 2, 3, and 4)

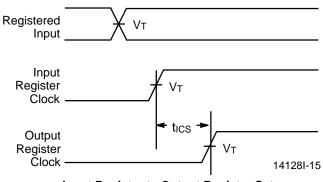




Gate Width (MACH 2, 3, and 4)



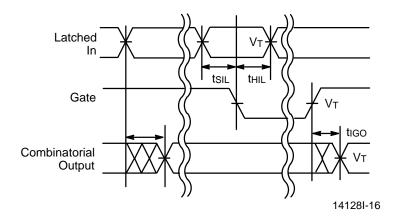
Registered Input (MACH 2 and 4)



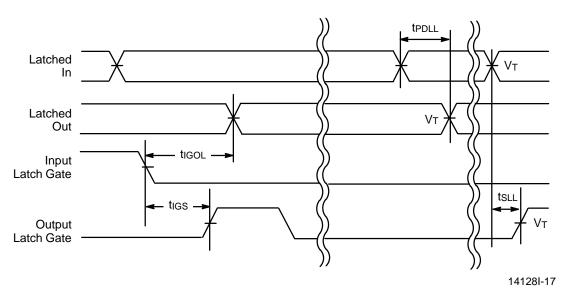
Input Register to Output Register Setup (MACH 2 and 4)

- 1. VT = 1.5 V.
- 2. Input pulse amplitude 0 V to 3.0 V.
- 3. Input rise and fall times 2 ns-4 ns typical.

SWITCHING WAVEFORMS



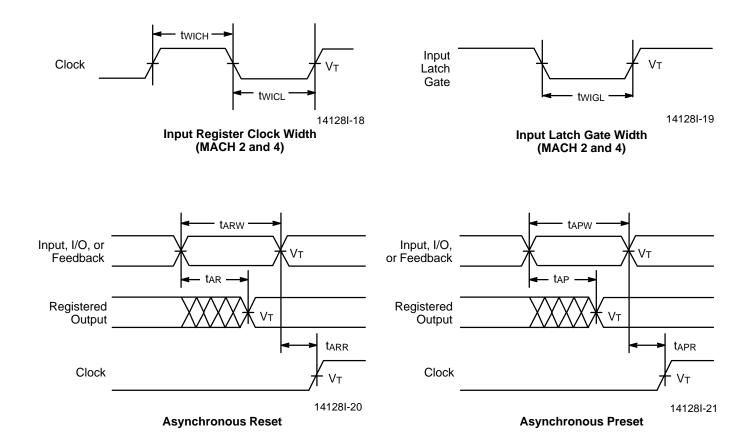
Latched Input (MACH 2 and 4)

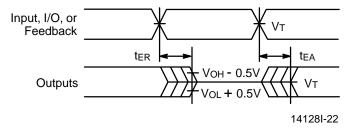


Latched Input and Output (MACH 2, 3, and 4)

- 1. VT = 1.5 V.
- 2. Input pulse amplitude 0 V to 3.0 V.
- 3. Input rise and fall times 2 ns-4 ns typical.

SWITCHING WAVEFORMS

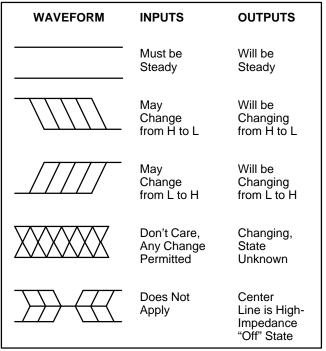




Output Disable/Enable

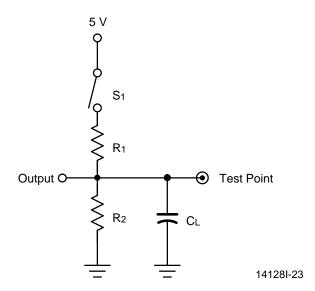
- 1. $V_T = 1.5 V$.
- 2. Input pulse amplitude 0 V to 3.0 V.
- 3. Input rise and fall times 2 ns-4 ns typical.

KEY TO SWITCHING WAVEFORMS



KS000010-PAL

SWITCHING TEST CIRCUIT



			Commercial		Measured
Specification	S ₁	C∟	R ₁	R ₂	Output Value
tpd, tco	Closed				1.5 V
t _{EA}	$Z \rightarrow H$: Open $Z \rightarrow L$: Closed	35 pF	300 Ω	390 Ω	1.5 V
ter	$H \rightarrow Z$: Open $L \rightarrow Z$: Closed	5 pF			$H \rightarrow Z: V_{OH} - 0.5 V$ $L \rightarrow Z: V_{OL} + 0.5 V$

^{*}Switching several outputs simultaneously should be avoided for accurate measurement.

fMAX PARAMETERS

The parameter f_{MAX} is the maximum clock rate at which the device is guaranteed to operate. Because the flexibility inherent in programmable logic devices offers a choice of clocked flip-flop designs, f_{MAX} is specified for three types of synchronous designs.

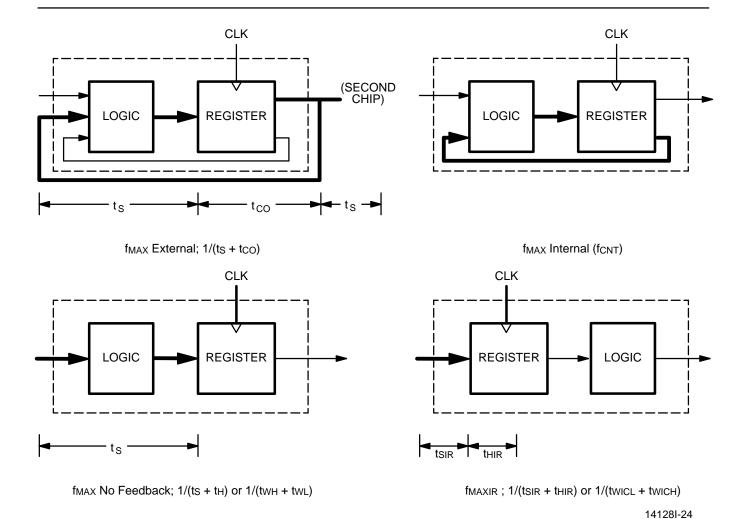
The first type of design is a state machine with feedback signals sent off-chip. This external feedback could go back to the device inputs, or to a second device in a multi-chip state machine. The slowest path defining the period is the sum of the clock-to-output time and the input setup time for the external signals ($t_{\rm S}+t_{\rm CO}$). The reciprocal, $f_{\rm MAX}$, is the maximum frequency with external feedback or in conjunction with an equivalent speed device. This $f_{\rm MAX}$ is designated " $f_{\rm MAX}$ external."

The second type of design is a single-chip state machine with internal feedback only. In this case, flip-flop inputs are defined by the device inputs and flip-flop outputs. Under these conditions, the period is limited by the internal delay from the flip-flop outputs through the internal feedback and logic to the flip-flop inputs. This f_{MAX} is designated " f_{MAX} internal". A simple internal counter is a good example of this type of design; therefore, this parameter is sometimes called " f_{CNT} ."

The third type of design is a simple data path application. In this case, input data is presented to the flip-flop and clocked through; no feedback is employed. Under these conditions, the period is limited by the sum of the data setup time and the data hold time ($t_S + t_H$). However, a lower limit for the period of each f_{MAX} type is the minimum clock period ($t_{WH} + t_{WL}$). Usually, this minimum clock period determines the period for the third f_{MAX} , designated " f_{MAX} no feedback."

For devices with input registers, one additional f_{MAX} parameter is specified: f_{MAXIR} . Because this involves no feedback, it is calculated the same way as f_{MAX} no feedback. The minimum period will be limited either by the sum of the setup and hold times $(t_{SIR} + t_{HIR})$ or the sum of the clock widths $(t_{WICL} + t_{WICH})$. The clock widths are normally the limiting parameters, so that f_{MAXIR} is specified as $1/(t_{WICL} + t_{WICH})$. Note that if both input and output registers are use in the same path, the overall frequency will be limited by t_{ICS} .

All frequencies except f_{MAX} internal are calculated from other measured AC parameters. f_{MAX} internal is measured directly.



ENDURANCE CHARACTERISTICS

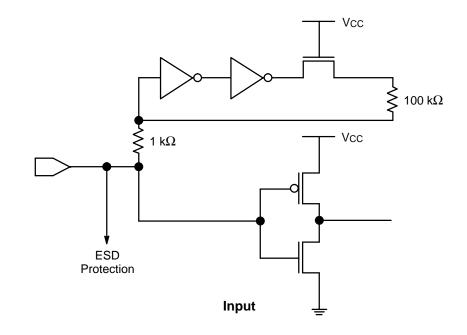
The MACH families are manufactured using our advanced Electrically Erasable process. This technology uses an EE cell to replace the fuse link used in

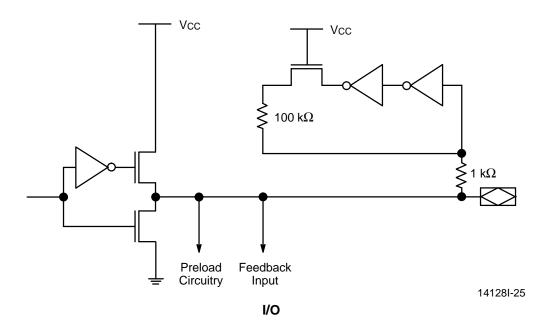
bipolar parts. As a result, the device can be erased and reprogrammed, a feature which allows 100% testing at the factory.

Endurance Characteristics

Parameter Symbol	Parameter Description	Min	Units	Test Conditions
		10	Years	Max Storage Temperature
t _{DR}	Min Pattern Data Retention Time	20	Years	Max Operating Temperature
N	Max Reprogramming Cycles	100	Cycles	Normal Programming Conditions

INPUT/OUTPUT EQUIVALENT SCHEMATICS





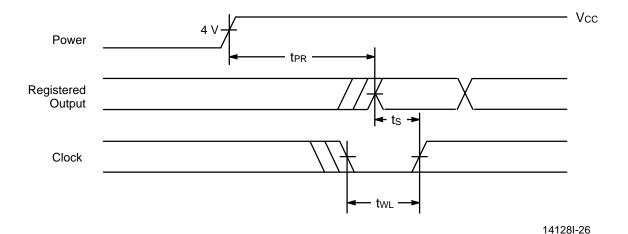
POWER-UP RESET

The MACH devices have been designed with the capability to reset during system power-up. Following power-up, all flip-flops will be reset to LOW. The output state will depend on the logic polarity. This feature provides extra flexibility to the designer and is especially valuable in simplifying state machine initialization. A timing diagram and parameter table are shown below. Due to the synchronous operation of the power-up reset and the

wide range of ways V_{CC} can rise to its steady state, two conditions are required to insure a valid power-up reset. These conditions are:

- 1. The Vcc rise must be monotonic.
- 2. Following reset, the clock input must not be driven from LOW to HIGH until all applicable input and feedback setup times are met.

Parameter Symbol	Parameter Descriptions	Max	Unit		
t _{PR}	Power-Up Reset Time	10	μs		
ts	Input or Feedback Setup Time	See			
twL	Clock Width LOW	Characteris	Switching Characteristics		



Power-Up Reset Waveform

USING PRELOAD AND OBSERVABILITY

In order to be testable, a circuit must be both controllable and observable. To achieve this, the MACH devices incorporate register preload and observability.

In preload mode, each flip-flop in the MACH device can be loaded from the I/O pins, in order to perform functional testing of complex state machines. Register preload makes it possible to run a series of tests from a known starting state, or to load illegal states and test for proper recovery. This ability to control the MACH device's internal state can shorten test sequences, since it is easier to reach the state of interest.

The observability function makes it possible to see the internal state of the buried registers during test by overriding each register's output enable and activating the output buffer. The values stored in output and buried registers can then be observed on the I/O pins. Without this feature, a thorough functional test would be impossible for any designs with buried registers.

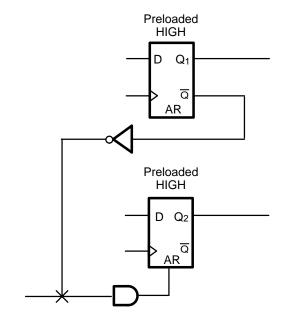
While the implementation of the testability features is fairly straightforward, care must be taken in certain instances to insure valid testing.

One case involves asynchronous reset and preset. If the MACH registers drive asynchronous reset or preset lines and are preloaded in such a way that reset or preset are asserted, the reset or preset may remove the preloaded data. This is illustrated in Figure 2. Care should be taken when planning functional tests, so that states that will cause unexpected resets and presets are not preloaded.

Another case to be aware of arises in testing combinatorial logic. When an output is configured as combinatorial, the observability feature forces the output into registered mode. When this happens, all product terms are forced to zero, which eliminates all combinatorial data. For a straight combinatorial output, the correct value will be restored after the preload or observe function, and there will be no problem. If the function implements a combinatorial latch, however, it relies on feedback to hold the correct value, as shown in Figure 3. As this value may change during the preload or observe operation, you cannot count on the data being correct after the operation. To insure valid testing in these cases, outputs that are combinatorial latches should not be tested immediately following a preload or observe sequence, but should first be restored to a known state.

All MACH 2 devices support both preload and observability.

Contact individual programming vendors in order to verify programmer support.



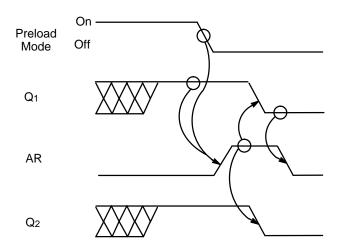


Figure 2. Preload/Reset Conflict

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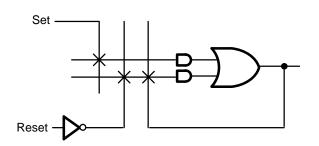


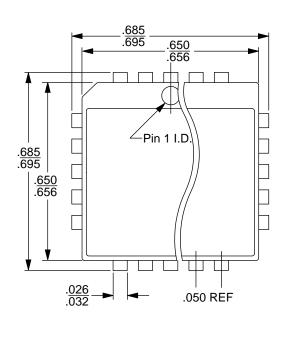
Figure 3. Combinatorial Latch

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PHYSICAL DIMENSIONS*

PL 044

44-Pin Plastic Leaded Chip Carrier (measured in inches)



TOP VIEW

.500 .590 REF .630 .013 .021

SIDE VIEW

.<u>062</u> .083

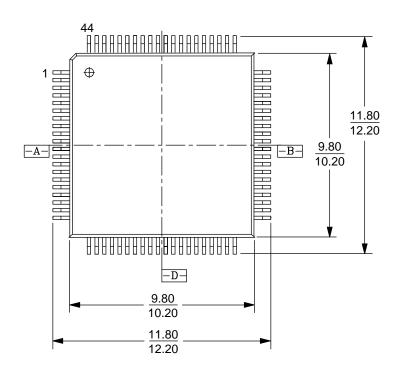
.<u>042</u> .056

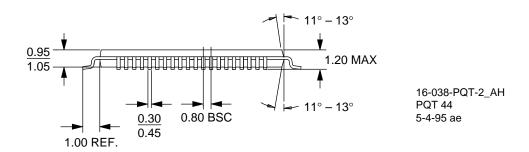
NG PLANE 16-038-SQ PL 044 DA78 6-28-94 ae

PHYSICAL DIMENSIONS*

PQT044

44-Pin Thin Quad Flat Pack (measured in millimeters)





^{*}For reference only. BSC is an ANSI standard for Basic Space Centering.